SCES105B - SEPTEMBER 1997- REVISED JANUARY 1998

- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Packaged in Plastic Small-Outline Transistor Package

# DCK PACKAGE (TOP VIEW) D 1 5 VCC CLK 2 GND 3 4 Q

#### description

This single positive-edge-triggered D-type flip-flop is designed for 2.3-V to 3.6-V  $V_{CC}$  operation.

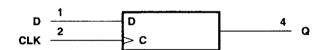
When data at the data (D) input meets the setup time requirement, the data is transferred to the Q output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

The SN74ALVC1G79 is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE**

INPL	JTS	OUTPUT			
CLK	Q				
1	Н	H			
1	L	L			
L_	Х	$Q_0$			

#### logic symbol†



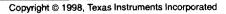
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

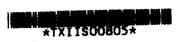


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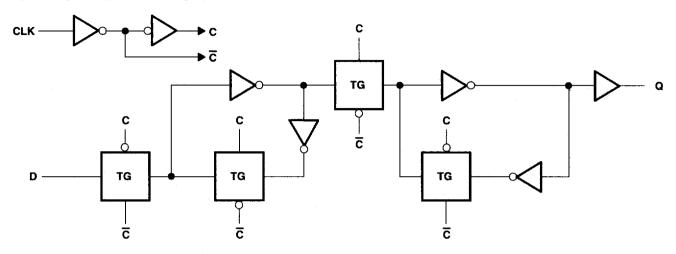
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#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Continuous output current, IO	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3)	389°C/W
Storage temperature range, T <sub>stq</sub>	65 C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 4.6 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



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#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage			3.6	٧
V.	High-level input voltage $ \frac{V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}}{V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}} $	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		٧
VIH		V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
	Law favol innot valle as	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V
VIL	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	Vcc	٧
٧o	Output voltage		0	Vcc	٧
	High-level output current	V <sub>CC</sub> = 2.3 V		-12	
ЮН		V <sub>CC</sub> = 2.7 V		-12	mA
		V <sub>CC</sub> = 3 V		-24	
	Low-level output current $ \begin{array}{c} V_{CC} = 2.3 \text{ V} \\ V_{CC} = 2.7 \text{ V} \\ V_{CC} = 3 \text{ V} \end{array} $	V <sub>CC</sub> = 2.3 V		12	
IOL		V <sub>CC</sub> = 2.7 V		12	mA
			24		
Δt/Δν	Input transition rise or fall rate		0	5	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	MIN TYPT	MAX	UNIT
	l <sub>OH</sub> = -100 μA	2.3 V to 3.6 V	V <sub>CC</sub> 0.2		
	I <sub>OH</sub> = -6 mA	2.3 V	2		
V		2.3 V	1.7		V
Voн	I <sub>OH</sub> = -12 mA	2.7 V	2.2		<b>'</b>
		3 V	2.4		
	I <sub>OH</sub> = -24 mA	3 V	2		
	I <sub>OL</sub> = 100 μA	2.3 V to 3.6 V		0.2	
	IOL = 6 mA	2.3 V		0.4	
VOL	la. 40 mA	2.3 V		0.7	٧
	IOL = 12 mA	2.7 V		0.4	
	I <sub>OL</sub> = 24 mA	3 V		0.55	
l <sub>1</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V		±5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		20	μΑ
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



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## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

		<u> </u>	V <sub>CC</sub> =		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency					•			MHz
tw	Pulse duration, CLK high or low	_							ns
		Data high							
t <sub>su</sub>	Setup time before CLK↑	Data low							ns
th	Hold time, data after CLK↑								ns

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

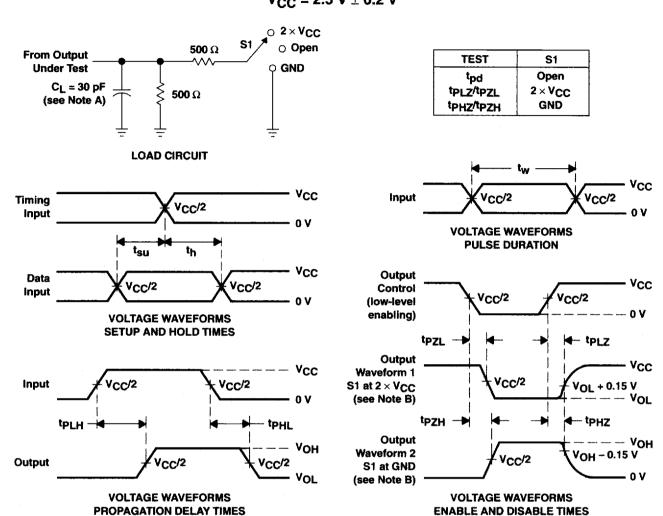
PARAMETER	FROM (INPUT)	TO V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V	V <sub>CC</sub> = 3.3 V ± 0.3 V	UNIT
	(1141-01)	(001701)	MIN MAX	MIN MAX	MIN MAX	
f <sub>max</sub>						MHz
t <sub>pd</sub>	CLK	Q				ns

#### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 2.5 V ± 0.2 V	V <sub>CC</sub> = 3.3 V ± 0.3 V	UNIT
			TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance	$C_L = 0$ , $f = 10 \text{ MHz}$			pF



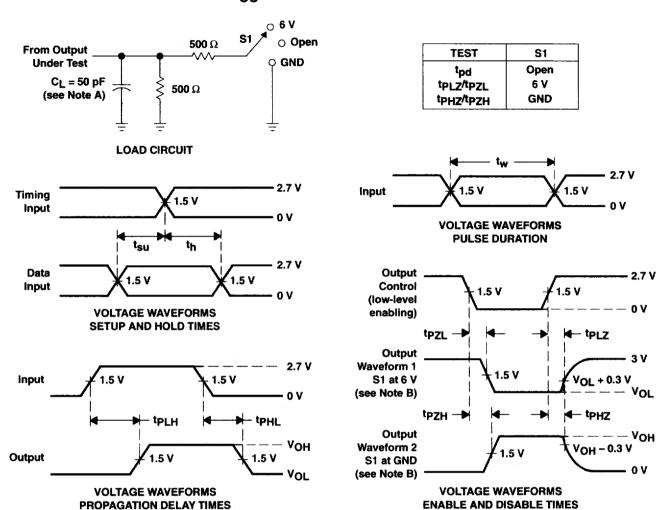
# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2 \text{ ns}$ ,  $t_f \leq 2 \text{ ns}$ .
  - D. The output is measured with one input transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

#### PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



- NOTES: A. CL includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ ,  $t_{f} \leq$  2.5 ns.  $t_{f} \leq$  2.5 ns.
  - The output is measured with one input transition per measurement.
  - E. tpLH and tpHL are the same as tpd.
  - F. tplz and tpHz are the same as tdis.
  - G. tpzi and tpzH are the same as ten.

Figure 2. Load Circuit and Voltage Waveforms

PRODUCI PREVIEW

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